

<b>L Number</b>	<b>Hits</b>	<b>Search Text</b>	<b>DB</b>	<b>Time stamp</b>
<b>92</b>	<b>25</b>	<b>(flexible with printed with wiring with board) same ((resin or epoxy or adhesive) with bump)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/09/14 15:38</b>
<b>93</b>	<b>3</b>	<b>(flexible with printed with wiring with board) same ((resin or epoxy) with bump with adhesive)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/09/14 15:44</b>
<b>94</b>	<b>9</b>	<b>((second or first or lower or upper or top or bottom) near (resin or epoxy or adhesive or coat or coating)) with bump) same (pcb or (printed adj wiring))</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/09/14 15:45</b>
<b>95</b>	<b>15</b>	<b>((second or first or lower or upper or top or bottom) near (resin or epoxy or adhesive or coat or coating)) with bump) same (pcb or (printed near2 board))</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/09/14 15:49</b>
<b>96</b>	<b>131</b>	<b>((second or first or lower or upper or top or bottom) near (resin or epoxy or adhesive or coat or coating)) with (ball or solder or bump)) same (pcb or (printed near2 board))</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/09/14 15:50</b>